MICROCHIP

3-Lead Deca-Watt Package, TO-252 (EA) - [DPAK]
Supertex Legacy Package Code K4

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

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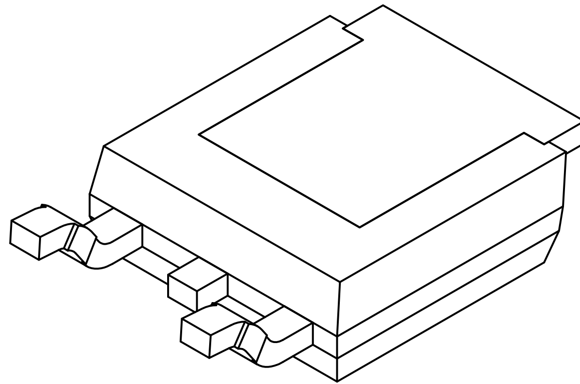

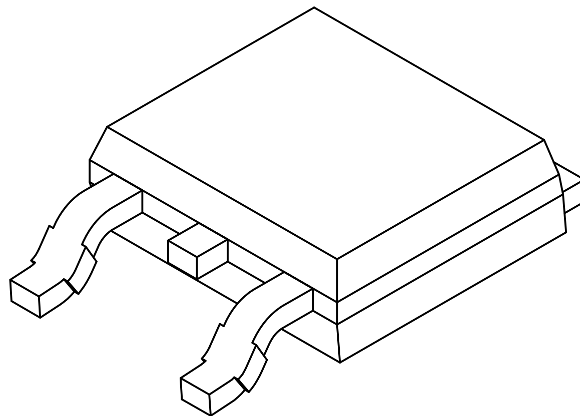

Units	INCHES		
	MIN	NOM	MAX
N (Leads)	3		
e	.090 BSC		
A	.086	-	.094
A1	.000	-	.005
b	.025	-	.035
b2	.030	-	.045
b3	.195	-	.215
c2	.018	-	.035
D	.235	.240	.245
D1	.205	-	.217
E	.250	-	.265
E1	.170	-	.200
H	.370	-	.410
L	.055	.060	.070
L1	.108 REF		
L2	.020 BSC		
L3	.035	-	.050
L4	.025	-	.040
L5	.035	-	.060
θ	0°	-	10°
θ1	0°	-	15°

Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

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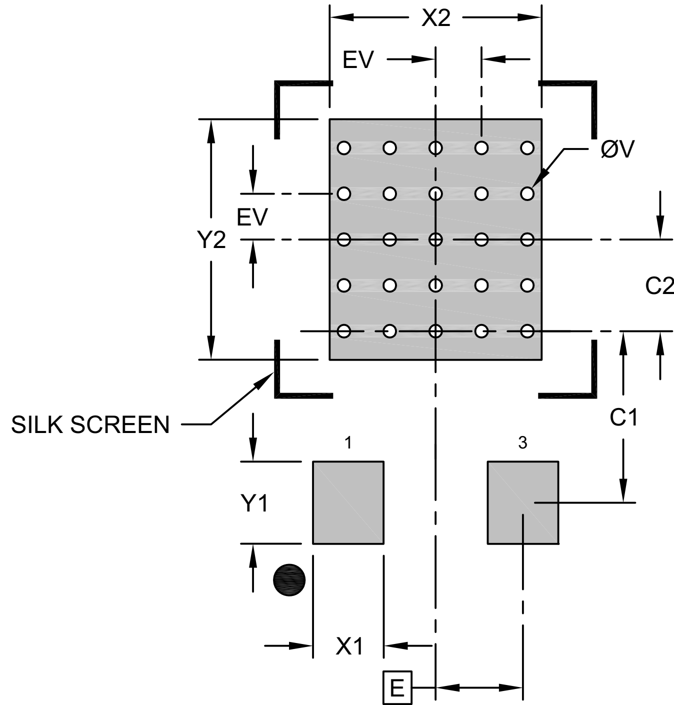

RECOMMENDED LAND PATTERN

Units	INCHES		
	MIN	NOM	MAX
E		.090	
X2			.219
Y2			.248
C1		.177	
C2		.094	
X1			.073
Y1			.085
V		.013	
EV		.047	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2189 Rev A

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